



Production Capability (Material)

No.Of Layer	14 max.
Board Thickness	0.2 - 5mm
Minimum Cort Thickness	0.15mm(included copper)
Board Thicknes Tolerance	±10%
Type of Material	FR4, High TG FR4, CEM-3, CEM-1, FR-2, FR-1
Surface Copper Thickness	5 oz max.
Inner Layer Copper Thickness	3 oz max.
Maximum Production Board Size	520 mm x 622 mm
Maximum Production Board Size	400 mm x 500 mm

Production Capability (Drilling)

Minimum Hole Diameter	0.2 mm
Maximum Hole Diameter	8.0 mm
Minimum Slot Width	0.6 mm
PTH Hole Size Tolerance	±0.075 mm
NPTH Hole Size Tolerance	±0.05 mm

Production Capability (Circuitry)

Minimum Annular Ring for 1/2 oz Copper	0.15 mm
Minimum Line Width/Space for 1/2 oz Copper	0.15 mm
Minimum Line Width/Space for 1 oz Copper	0.20 mm
Minimum Line Width/Space for 2 oz Copper	0.25 mm
Line Width After Etching	±10%
Impedance Control	normally ±10% (min. line width/space 5 mil/5 mil > 50 ohm)